

Abstract

The invention relates to a process for cutting laminates intended for application to the skin, comprising the following steps:

- a laminate comprising at least one film and at least one further layer is supplied,
- said laminate is transported to a cutting area of a laser beam cutting arrangement, whereby it is kept flat in the cutting area under a tension of between 0.1 N/m and 1×10^4 N/m,
- and said laminate is cut into or cut through by means of laser beams.